

Title (en)

A METHOD OF TESTING AND FITTING ELECTRONIC SURFACE-MOUNTED COMPONENTS

Title (de)

VERFAHREN ZUM PRÜFEN UND ANBRINGEN ELEKTRONISCHER FLACHBAUKOMPONENTEN

Title (fr)

PROCEDE DE CONTROLE ET DE FIXATION DE COMPOSANTS ELECTRONIQUES MONTES EN SURFACE

Publication

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Application

**EP 97930946 A 19970623**

Priority

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- SE 9602486 A 19960624

Abstract (en)

[origin: WO9750001A1] A method of testing and mounting electronic components that are to be surface-mounted. The components include on one side a plurality of contact pads that shall be connected electrically to contact pads on one side of a test board, particularly BGA components and corresponding components. The invention is characterized by applying to the component contact pads (2) a metal (5) which is liquid at room temperature or at an elevated room temperature, in a first method step; lifting the component (1) away from the surface of the metal (5) in a second method step, wherewith part (7) of the liquid metal remains on the component contact pads (2); and bringing the component contact pads (2) provided with the liquid metal into abutment with corresponding contact pads (3) on the test board (4), in a third method step.

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